Features

- Full TCPA V1.1b Compatibility
- Single Chip Turnkey Solution
- Hardware Asymmetric Crypto Engine
- 2048 RSA Sign in 500 ms Using CRT
- AVR 8-bit RISC Microprocessor
- Internal EEPROM Storage for 10+ RSA Keys
- 33 MHz LPC (Low Pin Count) Bus for Easy PC Interface
- Tamper Detectors for Physical or Environmental Attacks
- Secure Hardware and Firmware Design and Chip Layout
- True Random Number Generator (RNG)
- Secure Real-time Clock Option
- 3.3V ±10% Supply Voltage
- 28-lead TSSOP Package
- 0-70°C Temperature Range

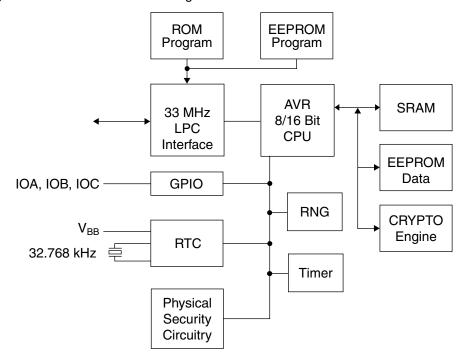
Description

The AT97SC3201 is a fully integrated security module designed to be integrated into personal computers and other embedded systems. It implements version 1.1b of the Trusted Computing Platform Alliance (TCPA) specification for Trusted Platform Modules (TPM).

The TPM includes a crypto accelerator capable of computing a 2048-bit RSA signature in 500 ms, and a 1024-bit RSA signature in 100 ms, both using CRT.

The chip communicates with the PC through the LPC interface, which runs at 33 MHz. In addition, it supports SIRQ (for interrupts) and CLKRUN (to permit clock stopping).

Figure 1. AT97SC3201 Block Diagram



The chip includes a full hardware random number generator that is used for the TCPA protocol and is also available to the system for any random numbers it may need during normal operation.



Trusted Platform Module

AT97SC3201

Summary

Rev. 2015AS-TCPA-07/02





A real-time clock function is available using an external battery and crystal. The chip provides tamper detection if the battery or crystal is removed or tampered with, and the current time value can be signed by the appropriate internal keys to verify its accuracy. (Contact Atmel for current status of this option.)

The battery detector can be used without the crystal for lower cost. In this mode, the TPM can indicate to the system if it has been removed from the PC in any way and also take actions internally.

The chip uses a dynamic internal memory management scheme to store from 10 to 20 keys. Other than the standard TCPA commands (TPM_Evictkey, TPM_Loadkey), no system intervention is required to manage this internal key cache.

The TPM is offered to OEM manufacturers as a turnkey solution, including the firmware integrated on the chip. In addition, Atmel provides the necessary driver software for integration into certain operating systems, along with BIOS drivers. (Contact Atmel for a complete list of operating systems supported.)

Full documentation for TCPA primitives can be found on the TCPA web site, www.trustedcomputing.org. This specification includes only mechanical, electrical and LPC protocol information.

Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification may cause temporary or permanent failure. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 1. DC Parameters

 $V_{CC} = 3.0$ to 3.6V; Temperature = 0 to 70° C

Symbol	Parameter	Min	Nom	Max	Units	Notes
V _{CC}	Supply Voltage	3.0	3.3	3.6	V	
I _{CC}	Operating Current at fclk = 33 MHz		25	50	mA	Note 1
I _{SB}	Standby Current, Chip Idle			100	μΑ	Note 1
I _{BB}	Battery Current		2	4	μΑ	Note 1. $V_{CC} = 0V$. fxtal = 0.
I _{LIO}	Input Leakage		0.1	3	μA	Vin = V _{CC} or GND
V _{IH}	Input High Threshold	0.5 x V _{CC}		V _{CC} + 0.5	V	
V _{IL}	Input Low Threshold	-0.5		0.3 * V _{CC}	V	
V _{OH}	Output High Voltage	0.9 x V _{CC}			V	At I _{OUT} = -500 μA
V _{OL}	Output Low Voltage			0.1 * V _{CC}	V	At I _{OUT} = 1.5 mA
I _{OH}		-24			mA	$V_{OUT} = .3 V_{CC}$
I _{OH}		-0.5			mA	$V_{OUT} = .9 V_{CC}$
I _{OH}				116	mA	V _{OUT} = .7 V _{CC}
I _{OL}		30			mA	$V_{OUT} = .6 V_{CC}$
I _{OL}		1.9			mA	$V_{OUT} = .1 V_{CC}$
I _{OL}				113	mA	V _{OUT} = .18 V _{CC}
I _{OLCR}	Output Low Current, CLKRUN#	7			mA	At V _{OUT} = .615 * V _{CC}
Cı	Input Pin Capacitance		6		pF	Note 2

Note:

Notes: 1. Values listed are advance information and are likely to change as production silicon is characterized.

2. These parameters guaranteed but not tested.





Table 2. AC Parameters

CI = 10 pf. V_{CC} = 3.0 to 3.7V; Temperature = 0 to 70°C

Symbol	Parameter	Min	Nom	Max	Units	Notes
T _{VAL}	CLK to Signal Valid Delay – LAD0-3	2		11	ns	Measured at Vtrise = $0.285 * V_{CC}$ and Vtfal = $0.615 * V_{CC}$. Measured from clk at Vtest = $0.4 * V_{CC}$.
T _{ON}	Float to Active Delay	2			ns	
T _{OFF}	Active to Float Delay			28	ns	
T _{SU}	Input Setup Time to CLK	7			ns	
T _H	Input Hold Time from CLK	0			ns	
T _{RST}	Reset Active Time After Power Stable	1			ms	Note 2
T _{RST-CLK}	Reset Active After CLK Stable	100			m	Note 2
T _{RST-OFF}	Reset Active to Output Float Delay			40	ns	Note 2
T _{RHFF}	RST# High to First FRAME# Assertion			500	clocks	
T _{CLKIN}	CLK Period	29.5	30	31	ns	Note 3
T _{CLKLO}	CLK Low Duration	13.4		18	ns	Note 1, Note 3
T _{CLKHI}	CLK High Duration	13.4		18	ns	Note 1, Note 3

Note:

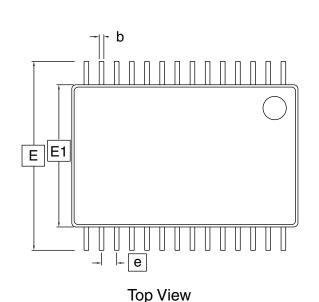
- 1. All parameters measured with respect to signal crossing Vtest = 0.4 * V_{CC} unless otherwise noted.
- 2. These parameters guaranteed but not tested.
- 3. The minimum parameter must never be violated under any circumstances unless Ireset# is asserted. If proper CLKRUN# signaling is observed, the maximum specification can be violated.

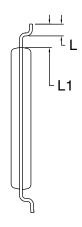
Table 3. Ordering Information

Ordering Code	Package	Operation Range	
AT97SC3201-01AC	28A	Commercial	
		(0° to 70° C)	

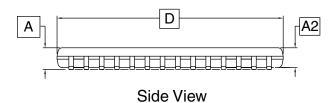
Package Drawing

Figure 2. 28A3 - TSSOP





End View



COMMON DIMENSIONS

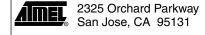
(Unit of Measure = mm)

SYMBOL	YMBOL MIN NOM		MAX	NOTE		
D	D 9.60 9.70		9.80	2, 5		
Е		8.10 BSC				
E1	6.00	6.10	6.20	3, 5		
Α	_	_	1.20			
A2	0.80	1.00	1.05			
b	0.19	_	0.30	4		
е	e 0.65 BSC					
L	0.45	0.60	0.75			
L1	1.00 REF					

Notes:

- 1. This drawing is for general information only. Please refer to JEDEC Drawing MO-153, Variation DB for additional information.
- 2. Dimension D does not include mold Flash, protrusions or gate burrs. Mold Flash, protrusions and gate burrs shall not exceed 0.15 mm (0.006 in) per side.
- 3. Dimension E1 does not include inter-lead Flash or protrusions. Inter-lead Flash and protrusions shall not exceed 0.25 mm (0.010 in) per side.
- 4. Dimension b does not include Dambar protrusion. Allowable Dambar protrusion shall be 0.08 mm total in excess of the b dimension at maximum material condition. Dambar cannot be located on the lower radius of the foot. Minimum space between protrusion and adjacent lead is 0.07 mm.
- 5. Dimension D and E1 to be determined at Datum Plane H.

1/8/02



IIILE
28A3, 28-lead, 6.1 x 9.7 mm Body, 0.65 pitch
Thin Shrink Small Outline Package (TSSOP)

DRAWING NO. 28A3 A





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